

MATERIALS & FINISHES

BODY: BRASS
PLATED GOLD

CONTACT: BERYLLIUM COPPER
PLATED GOLD

INSULATOR: TEFLON

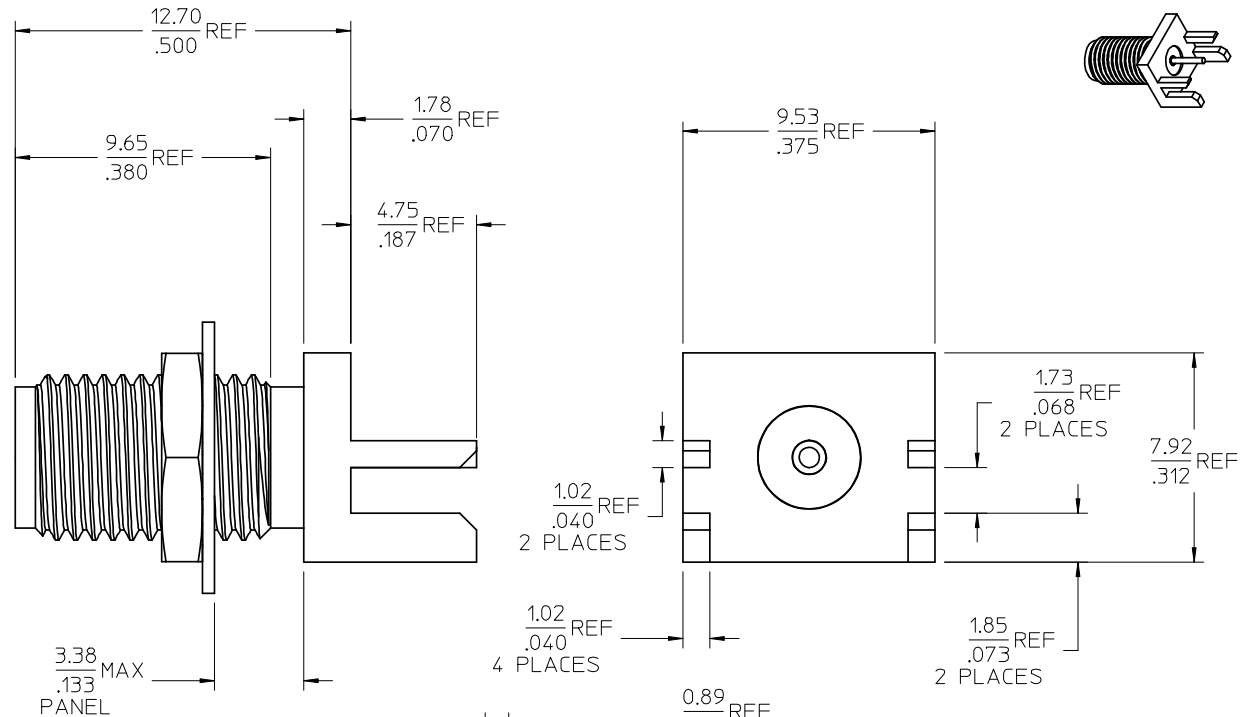
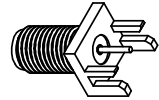
JAM NUT: BRASS
PLATED GOLD

LOCK WASHER: PHOSPHOR BRONZE
PLATED GOLD

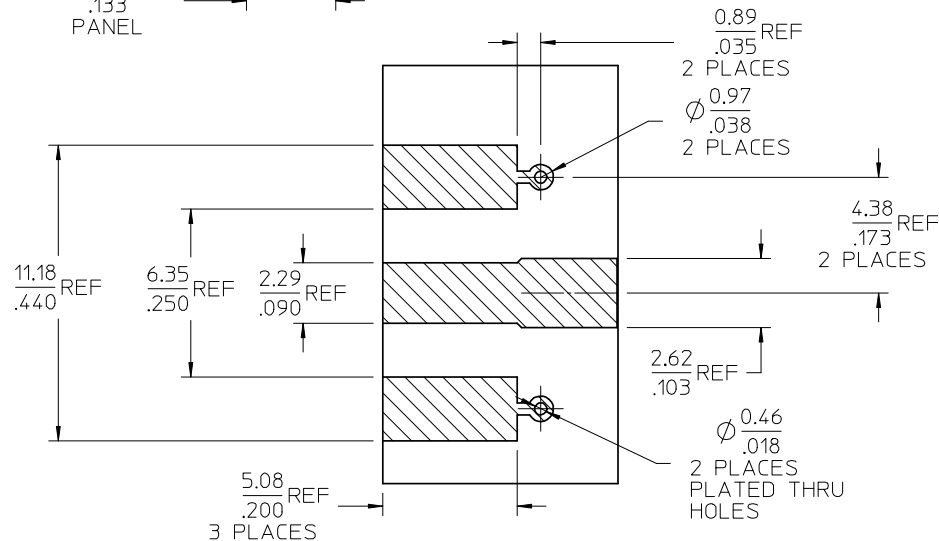
HARDWARE:

JAM NUT: 7.87/.310 HEX X 1.55/.061

LOCK WASHER: \varnothing 10.26/.404 X \varnothing 6.65/.262 X .46/.018



RECOMMENDED PCB LAYOUT
BOARD THICKNESS 1.57/.062



PART # 73251-1290

MIL-STD-348A, FIG. 310.2	INTERFACE
SPECIFICATION	DESCRIPTION

CHG: UPDATED VIEW OF REVISED BODY.	EC NO: URF2008-0633	2008/06/11
	DRWN:ROBERTSON	2008/06/11
DESCRIPTION	CHKD:SSS	2008/06/11
	APPR:JWIENER	2008/06/11
REV	A1	

QUALITY SYMBOLS	$\blacktriangledown=0$	$\blacktriangledown=0$
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GENERAL TOLERANCES (UNLESS SPECIFIED)	mm	INCH
4 PLACES	\pm .005	\pm .0002
3 PLACES	\pm .005	\pm .0002
2 PLACES	\pm .005	\pm .0002
1 PLACE	\pm .005	\pm .0002
ANGULAR \pm 2°		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		

DIMENSION STYLE		SCALE
MM/IN		DESIGN UNITS
DRAWN BY		DATE
SSS		2000/08/00
CHECKED BY		DATE
SSS		2000/08/00
APPROVED BY		DATE
GMH		2000/08/00
MATERIAL NO.		DOCUMENT NO.
732511290		SD-73251-129
SIZE		SHEET NO.
C		1 OF 1

THIRD ANGLE PROJECTION	
TITLE	
SMA, JACK EDGEMOUNT FOR .062 PCB SMA-J/PCB, EWR-2864	
MOLEX INCORPORATED	
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